CLAIMS

1. A photosensitive resin composition comprising an alkali-soluble polymer (A-1), a glass filler (B), a photopolymerizable compound (C), a photopolymerization initiator (D), and a thermal crosslinking agent (E),

wherein the glass filler (B) has a refractive index of 1.55 to 1.75 at a wavelength of 405 nm,

wherein the glass filler (B) contains silicon oxide and aluminum oxide, and further contains yttrium oxide or lanthanoid oxide.

2. The photosensitive resin composition according to claim 1, wherein a content of yttrium oxide or lanthanoid oxide in 100 wt% of the glass filler (B) is 15 to 35 wt%.

3. The photosensitive resin composition according to claim 1 or 2, wherein a total amount of magnesium ions, calcium ions, and zinc ions detected in an extract obtained by performing an extraction treatment on the glass filler (B) under a saturated water vapor pressure condition at 121°C for 24 hours is 100 ppm or less.

4. The photosensitive resin composition according to any one of claims 1 to 3, wherein an absolute value of a difference

between a refractive index of the glass filler (B) and a refractive index of an organic component (excluding a solvent) obtained by removing the glass filler (B) from the photosensitive resin composition is 0.05 or less.

5. The photosensitive resin composition according to any one of claims 1 to 4, wherein the photopolymerizable compound (C) has one or both of an acrylic group and a glycidyl group.

6. The photosensitive resin composition according to any one of claims 1 to 5, wherein the alkali-soluble polymer (A-1) is polyimide having one or both of a phenolic hydroxyl group and a carboxyl group as an alkali-soluble group.

7. A photosensitive resin sheet comprising at least a layer formed of the photosensitive resin composition according to any one of claims 1 to 6 (a photosensitive resin layer) and a film that supports the layer (a support film).

8. The photosensitive resin sheet according to claim 7, wherein the support film has an oxygen permeability of 10 to 400 cc/m^2 and a haze of 0.1 to 1.5%.

9. The photosensitive resin sheet according to claim 7 or 8, wherein the photosensitive resin sheet is used as a wall

material or a roof material for forming a hollow structure.

10. A cured material obtained by curing the photosensitive resin composition according to any one of claims 1 to 6 or the photosensitive resin layer in the photosensitive resin sheet according to any one of claims 7 to 9.

11. The cured material according to claim 10, wherein a water vapor permeability is 50 to 250 g/(m^2•day).

12. A hollow structure comprising:

a substrate;

a convex portion that is formed on the substrate and is provided to surround a part of a surface of the substrate; and

a film-shaped material that is in contact with a top of the convex portion and is formed of the cured material according to claim 10 or 11,

wherein a space (a hollow portion) closed by the substrate, the convex portion, and the film-shaped member is formed.

13. The hollow structure according to claim 12, wherein an area of the substrate in the hollow portion is 0.01 to 1.0 mm^2.

14. The hollow structure according to claim 12 or 13, wherein a width of the convex portion is 15 to 300 μm.

15. The hollow structure according to any one of claims 12 or 13, wherein the convex portion contains polyimide.

16. A method for producing the hollow structure according to claim 12, the method comprising the following steps 1 to 6 in this order:

step 1: a step of forming the convex portion on the substrate;

step 2: a step of bonding the photosensitive resin layer side of the photosensitive resin sheet according to any one of claims 7 to 9 to the convex portion formed on the substrate;

step 3: a step of exposing the photosensitive resin layer through the support film;

step 4: a step of peeling off the support film;

step 5: a step of developing the photosensitive resin layer; and

step 6: a step of thermally curing the photosensitive resin layer to form a cured material.

17. An electronic component comprising the hollow structure according to any one of claims 12 to 15.

18. An elastic wave filter comprising the hollow structure according to any one of claims 12 to 15.

19. An electronic component comprising the cured material according to claim 10 or 11.